



AMENDMENTS TO THE SPECIFICATION

Please replace paragraph [1] beginning at page 1, line 9, with the following rewritten paragraph:

--This application is related to U.S. Patent Application No. 10/734,704 (~~Attorney Docket~~
5 ~~No. LAM2P461~~), filed on even date herewith, and entitled "Method and Apparatus for
Semiconductor Wafer Planarization." The disclosure of this related application is
incorporated herein by reference.--

Please change the title to the following: METHOD AND APPARATUS FOR
10 MATERIAL DEPOSITION IN SEMICONDUCTOR FABRICATION.